

**TIM-PUTTY** is ‘Ultra Soft’ and highly conformable paste-type gap filler. Its “ultra soft” consistency assures efficient heat transfer between delicate parts where minimum pressure can be tolerated. This Form-in-place gap filler is ideal for applying any thickness with little or no stress. It is designed to provide a thermal solution for the recent trends of integrating higher frequency electronics in to smaller devices. **TIM-PUTTY** easily forms and adheres to most surfaces, shapes and sizes of components with very low compression force.



**TIM-PUTTY**

Form-in-place, Thermally Conductive  
Gap Filler Putty

| PROPERTY                                 | 418              | 519              |
|--|------------------|------------------|
| Type                                     | Non-Silicone     | Silicone         |
| Consistency                              | Soft Paste       | Soft Paste       |
| Color                                    | Gray             | White            |
| Density, g/cc                            | 2.7              | 2.8              |
| Thermal Conductivity, W/m <sup>2</sup> K | 2.1              | 1.5              |
| Service Temperature, °C                  | -50 to 200 °C    | -50 to 200 °C    |
| Volume Resistivity, Ohm-cm               | 10 <sup>12</sup> | 10 <sup>12</sup> |
| Dielectric Strength, Volts/Mil           | 392              | 500              |
| Dielectric constant                      | 4.5              | 5.0              |
| TGA Weight Loss, %/Wt, (150°C/24 hrs)    | 0.1              | 0.1              |
| Compressibility, @ 5 psi                 | 25%              | 30%              |
| Flame Retardancy                         | V-O Equivalent   | V-O Equivalent   |

**Key Features**

- High Thermal Conductivity up to 2.1 W/m<sup>2</sup>K
- Requires No Curing.
- Stress Absorbing Flexibility and vibration dampening.
- Eliminate specific pad thickness and die-cut shapes.
- Electrically Isolating.
- “Form-in-Place” gap filler and remain form stable.
- Relieves CTE stresses during thermal cycling.

**Applications**

- Filling various gaps between heat generating devices to heat sinks and housings.
- Useful where systems need to be taken a part and reassembled during production or maintenance.
- To interface components with delicate leads.
- To fill gaps where surfaces are irregular or large.

**Availability:**

**TIM-PUTTY** generally supplied in 30cc Syringe, 6 & 12 oz cartridge or 5 gallon pail.

**Disclaimer:** All data given here is offered as a guide to the use of these materials and not as a guarantee of their performances. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not be construed as recommendations to infringe any patent